## **Surface Mount Thin-Film Filters**

 $50\Omega$ DC to 40 GHz

## The Big Deal

- Low passband insertion loss
- High rejection
- Good power handling
- Temperature stability -55°C to 125°C
- High repeatability
- RoHS complaint
- Small size



### **Product Overview**

Mini-Circuits' Surface Mount Thin-Film filters offer low insertion loss and high rejection realized via Thin-Film on Alumina substrate, using a sputtering process that can guarantee a enhanced Q and repeatable performance.

Low pass, high pass and bandpass surface mount thin-film designs can be realized with this technology. Using thin-film manufacturing, we can guarantee repeatability on large batches of filters. Thin-film filters are small in size with high-quality, precise machining for applications where size is critical.

## **Key Features**

Feature	Advantages			
Low insertion loss	High Q material and sputtering process results in lower insertion loss, better SNR is obtained.			
Fast roll-off (steeper skirts)	gh selectivity results in better adjacent channel rejection and dynamic range			
Wider stopband	Wide spur-free stopband results in better adjacent channel rejection and dynamic range			
Temperature stability	Very minimal change in electrical performance across temperature makes these filters suitable for a wide range of operating conditions.			
Small Size	Various design techniques are employed to realize small size.			



Notes
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C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/MCLStore/terms.jsp



· Low mid band insertion loss of 1.6 dB typ.

• 15 dB typ. return loss in entire passband

# **Bandpass Filter**

 $50\Omega$ 26500 to 29500 MHz

## ABF-28G+



Generic photo used for illustration purposes only

CASE STYLE: VG3044

### Electrical Specifications(1) at 25°C

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Paran	Parameter		Frequency (MHz)	Min.	Тур.	Max.	Unit
	Center Frequency	Fc	28000	_	1.6	3.0	dB
Pass Band	Insertion Loss	F1-F2	26500 - 29500	_	3.5	_	dB
	Return Loss		26500 - 29500	_	15	_	dB
Cton Bond Lower	Insertion Loss	DC-F3	DC - 23000	30	45	_	dB
Stop Band, Lower	Insertion Loss	F3-F4	23000 - 24500	25	45	_	dB
		F5-F6	31500 - 32500	25	55	_	dB
Stop Band, Upper	Insertion Loss	F6-F7	32500 - 36000	40	60	_	dB
		F7-F8	36000 - 40000	_	40	_	dB

<sup>1.</sup> Measured on Mini-Circuits Characterization Test Board TB-ABF-28G+

Maximum Ratings						
Operating Temperature	-55°C to 125°C					
Storage Temperature	-55°C to 125°C					
RF Power Input	1W Max. @ 25°C					

Permanent damage may occur if any of these limits are exceeded.

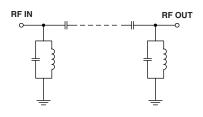
### **Applications** • n257

• 60 dB typ. rejection · Shielded component

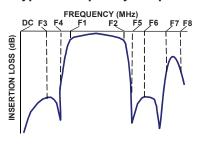
**Features** 

• 5G Telecommunication

### **Functional Schematic**



### **Typical Frequency Response**

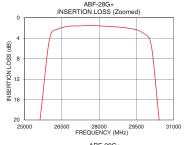


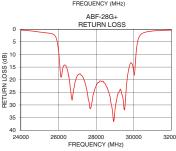
### +RoHS Compliant

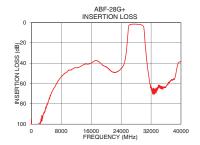
The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

## Typical Performance Data at 25°C

Frequency (MHz)	Insertion Loss (dB)	Return Loss (dB)
10	107.70	0.03
1000	104.11	0.19
10000	47.03	0.07
23000	48.45	0.06
24500	43.04	0.68
25350	29.81	1.47
25600	20.76	1.72
26100	2.78	17.77
26500	1.92	17.16
27000	1.63	18.35
28000	1.58	22.45
29000	1.93	31.81
29500	2.33	31.96
29800	3.07	13.85
30425	20.51	1.83
30650	30.02	1.14
31500	55.78	0.48
32500	65.52	0.34
36000	63.14	0.06
40000	38.60	1.13





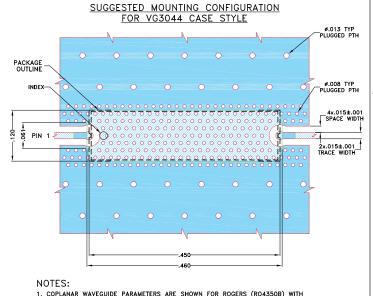


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### **Pad Connections**

RF IN	1
RF OUT	2
GROUND	3

### Demo Board MCL P/N: TB-ABF-28G+ Suggested PCB Layout (PL-713)



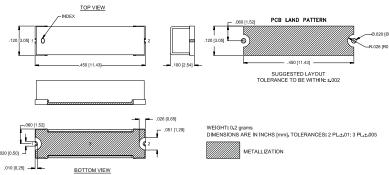
DIELECTRIC THICKNESS .0066±.0007. COPPER: 1/2 Oz. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.

DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)

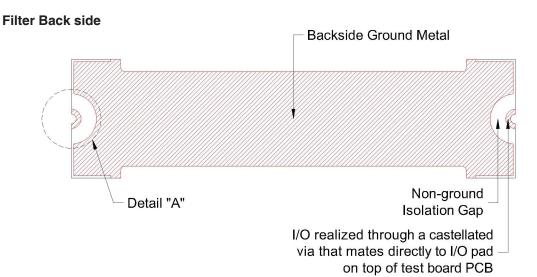
2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

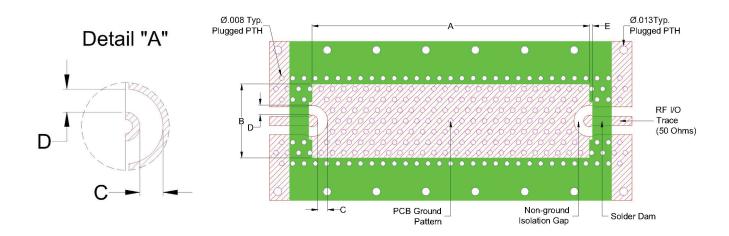
### **Outline Drawing**



## Recommendations of PCB pattern at customer board



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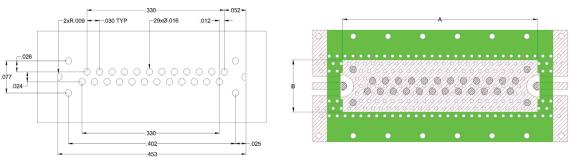
- 1) Customer PCB's ground pattern length (dimension A) can be similar to filter length.
- 2) Customer PCB's ground pattern width (dimension B) can be similar filter width.
- 3) Dimensions C and D on Filter RF I/O detail and Customer PCB pattern can be closely match. The dimensions of C and D on the Customer PCB pattern can be slightly larger to account for component alignment tolerance (ground metal can be pulled back from RF I/O trace).
- 4) Recommend to use solder mask at Customer PCB at outer area of filter pattern/footprint without any clearance.
- 5) Recommended to use Solder mask at I/O of Customer PCB with 5 mil clearance from filter I/O edge (dimension E)

### Comments on component handling and solder attach

- 1) Avoid using soldering iron directly to the ceramic filter. This would lead to development of crack in the component due to thermal shock.
- 2) Vacuum pick-up tool or plastic tweezers are recommended for handling the components. Extra care should be taken not to scratch the filter or metal area.
- 3) Use 2-3 mil thickness stencil plate and screen print the solder. Refer below picture for recommended stencil pattern to get the best solder attachment.

## Stencil opening drawing

### Solder location after screen print



- 4) Plugged ground vias in the PWB will improve attachment consistency.
- Recommended to have a similar or closer test board material and thickness (refer Mini-Circuits evaluation board for details) to minimize the CTE over the temperature range.

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## Typical Performance Data

FREQ.	Insertion Loss	Input Return Loss	Output Return Loss	
(MHz)	(dB)	(dB)	(dB)	
10	107.70	0.03	0.03	
50	95.69	0.06	0.07	
100	113.58	0.12	0.11	
500	122.33	0.18	0.18	
1000	104.11	0.19	0.18	
2000	103.58	0.13	0.14	
3000	94.21	0.03	0.05	
4000	82.99	0.10	0.10	
5000	73.00	0.04	0.06	
6000	64.60	0.03	0.02	
7000	58.34	0.00	0.04 0.04	
8000 9000	53.39 50.09	0.09 0.06	0.04	
10000	47.03	0.00	0.03	
11000	45.81	0.10	0.10	
12000	44.47	0.05	0.05	
13000	43.58	0.03	0.02	
14000	41.41	0.07	0.05	
15000	41.00	0.12	0.11	
18000	38.42	0.36	0.40	
20000	43.82	0.30	0.30	
20500	44.78	0.23	0.22	
21000	46.76	0.17	0.14	
22000	49.11	0.05	0.05	
23000	48.45	0.06	0.06	
24500	43.04	0.68	0.71	
25350	29.81	1.47	1.54	
25600 25825	20.76 10.78	1.72	1.79 2.92	
26100	2.78	2.80 17.77	19.97	
26500	1.92	17.16	17.54	
27000	1.63	18.35	19.06	
27500	1.54	23.93	27.89	
27800	1.53	27.88	27.99	
28000	1.58	22.45	24.38	
28200	1.63	20.48	20.67	
28500	1.72	21.91	20.53	
29000	1.93	31.81	24.42	
29500	2.33	31.96	33.18	
29800	3.07	13.85	13.37	
30225	10.50	4.29	4.17	
30425	20.51	1.83	1.80	
30650	30.02	1.14	1.22 0.87	
31000 31200	42.14 47.81	0.73 0.59	0.87 0.76	
31500	55.78	0.59	0.76	
31800	61.50	0.45	0.60	
32000	63.53	0.39	0.56	
32300	65.07	0.35	0.50	
32500	65.52	0.34	0.48	
32800	71.01	0.31	0.41	
33000	68.79	0.27	0.38	
33500	66.81	0.27	0.28	
34000	61.52	0.22	0.16	
34500	63.33	0.17	0.07	
35000	64.94	0.10	0.02	
36000	63.14	0.06	0.04	
38000	56.32	0.79	1.29	
39000	42.99	4.26	4.69	
40000	38.60	1.13	0.89	

FREQ.	Group Delay
(MHz)	(ns)
(MHz)  26500 26550 26600 26650 26700 26750 26800 26850 26900 26950 27000 27150 27100 27150 27200 27250 27300 27350 27400 27450 27500 27550 27600 27650 27650 27650 27650 27700 27750 28000 28550 28300 28150 28200 28250 28300 28350 28400 28450 28450 28500 28550	(ns)  0.70 0.68 0.66 0.65 0.64 0.62 0.61 0.60 0.59 0.58 0.57 0.56 0.55 0.54 0.54 0.53 0.53 0.53 0.53 0.53 0.52 0.52 0.52 0.52 0.52 0.52 0.51 0.51 0.51 0.51 0.51 0.51 0.51 0.51
28600 28650 28700 28750	0.52 0.52 0.53 0.53
28800 28850 28900 28950 29000 29050 29100	0.53 0.54 0.54 0.55 0.55 0.56 0.57
29100 29150 29200 29250 29300 29350 29400	0.57 0.57 0.58 0.59 0.60 0.61 0.62



0.65

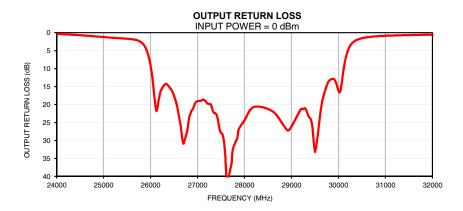
## Typical Performance Curves

30 35

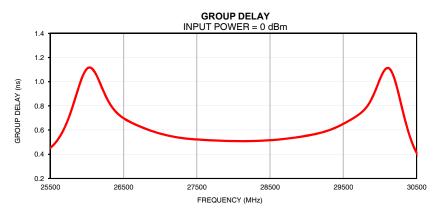
24000

26000

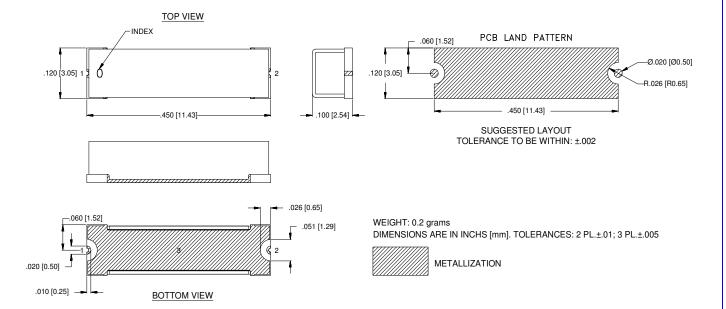




28000 FREQUENCY (MHz)



## **Outline Dimensions**



### **Notes:**

- Case material: Gold over Nickel over Annealed Stainless Steel.
- Base: Ceramic
- Termination finish: as shown below or indicated on Data Sheet.

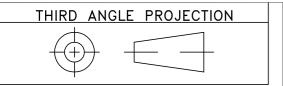
Gold over Nickel plate. All models, (+) suffix. For RoHS Case Styles:





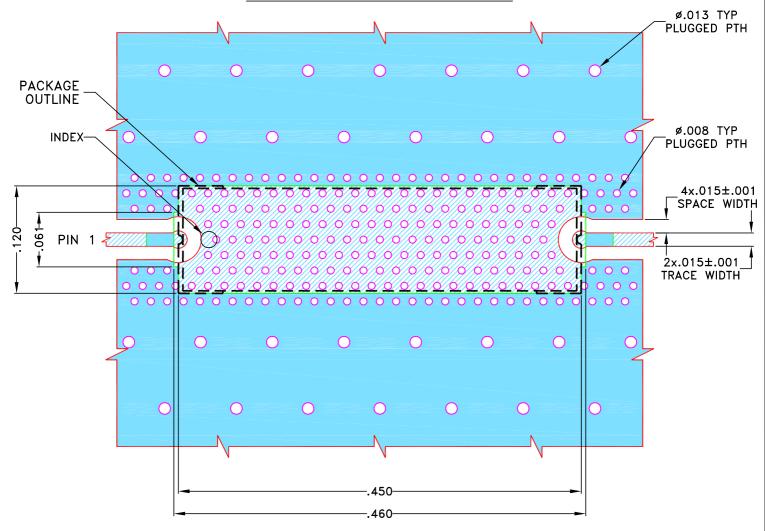
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site

The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com



		REVISIONS			
REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	NPO-001850	NEW RELEASE	JUL 21	DDR	VC

# SUGGESTED MOUNTING CONFIGURATION FOR VG3044 CASE STYLE



## NOTES:

- 1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (RO4350B) WITH DIELECTRIC THICKNESS .0066±.0007. COPPER: 1/2 Oz. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
- 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

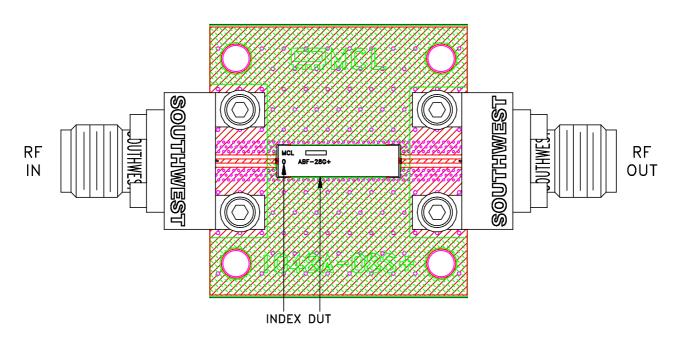
DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)

DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

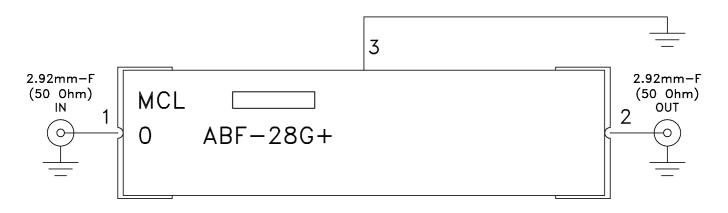
UNLESS OTHERWISE SPECIFIED		INITIALS	DATE					• 4 (R)			
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3 PL DECIMALS ± .005	APPROVED	NN	06 JUL 21								
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☐ Mini−Circuits ®				,			,		,		
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ASHFFTA1 DWG REV-A DATF-01/12/95		1 90	3-PL-713		9:1		1				

## Evaluation Board and Circuit

TB-ABF-28G+



## Schematic diagram



### Notes:

1. PCB Material: ROGERS (RO4350B) OR Equivalent, Dielectric Constant= $3.48\pm.05$  Dielectric Thickness: .0066"  $\pm$  .0007"

2. 50 Ohm 2.92mm Female Connectors.

Mini-Circuits®



**ENV120** 



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Solderability	10X Magnification	J-STD-002, Para 4.2.5, Test S, 95% Coverage
Thermal Shock	-55° to 125°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, Except +125°C

ENV120 Rev: OR

04/30/21

DCO-0453 File: ENV120.pdf